

In the Specification:

Please **replace** the paragraph at **page 2, lines 22 to 27**, with a replacement paragraph amended as follows:

In accordance with a first embodiment of the invention, this object is satisfied by a single semiconductor element having the features ~~of claim 1 and in particular in~~ that the contact side of the semiconductor element is provided with a glass passivation layer which surrounds the solder contacts around the periphery at the contact side of the single semiconductor element.

Please **replace** the paragraph at **page 6, lines 13 to 18**, with a replacement paragraph amended as follows:

In accordance with a second embodiment, the explained object is satisfied by a single ~~semi-conductor~~ semiconductor element having the features ~~of claim 8 and in particular in~~ that at least one side face of the single semiconductor element is provided at least partly with an insulator layer for the avoidance of short circuits on the soldering of the single semiconductor element to the carrier board.

Please **replace** the paragraph at **page 8, lines 22 to 25**, with a replacement paragraph amended as follows:

The explained object is satisfied in accordance with a third embodiment by a single semiconductor element having the features ~~of claim 18 and in particular in~~ that the at

least two solder contacts have different outlines at the contact side of the single semiconductor element.

Please **replace** the paragraph at **page 15, lines 9 to 20**, with a replacement paragraph amended as follows:

A further advantage lies in the fact that this additional side insulation can be produced without any large additional effort as part of a customary production process. Starting from a common substrate, a plurality of similar single semiconductor elements can namely be produced in that the respective active layer 15 is produced with a cathode 17 and an anode 19 along a pre-determined arrangement pattern within an electrically active region 21. ~~[[The]]~~ Along a grid, the substrate is provided with dividing trenches ~~along a grid~~ which extend between the respective electrically active regions 21 and are, for example, ~~etched~~ etched into the substrate. Subsequently, the substrate surface, including the dividing trenches etched into it, is provided with the oxide layer 25. The substrate is then sawn apart along the dividing trenches.

[RESPONSE CONTINUES ON NEXT PAGE]